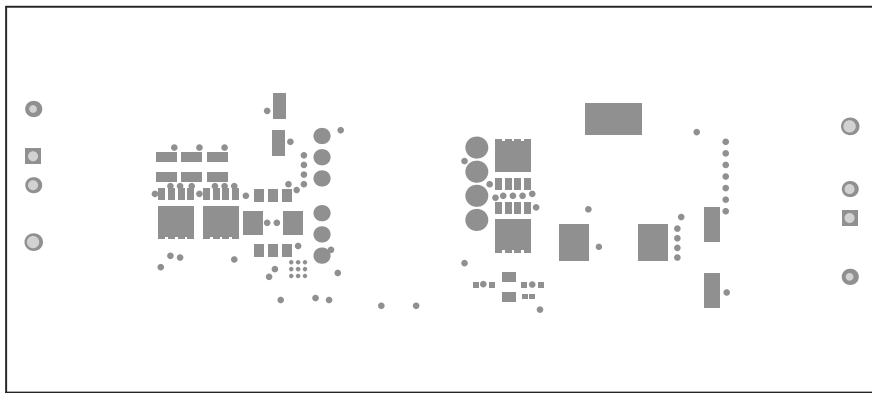
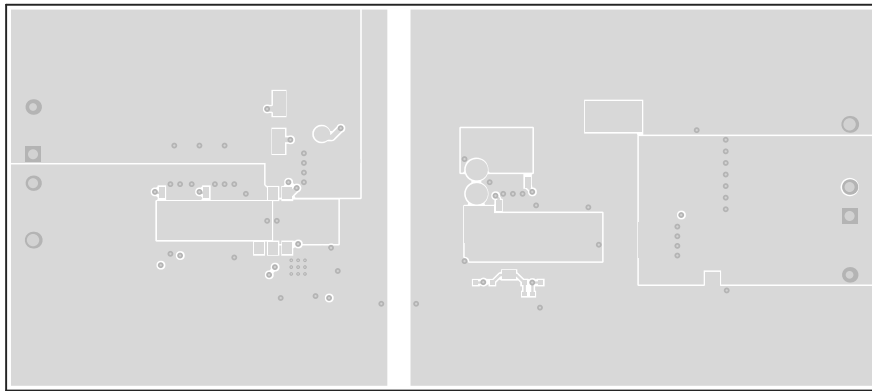


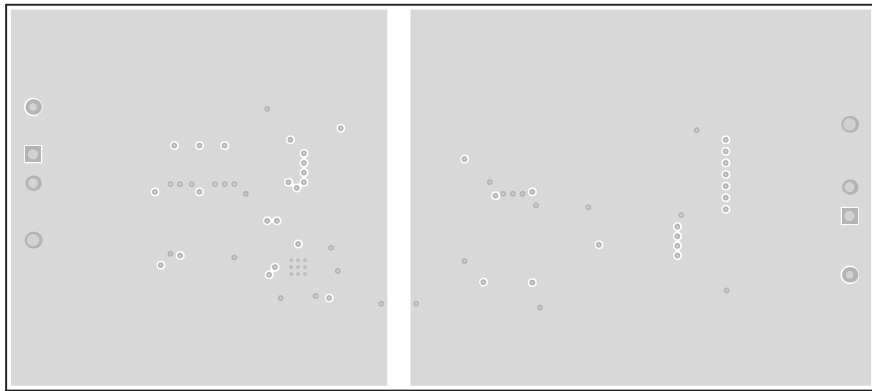
| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9720 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | | | |
| PLOT NAME = Top Overlay | GENERATED : 5/20/2014 12:26:15 PM | TEXAS INSTRUMENTS | |



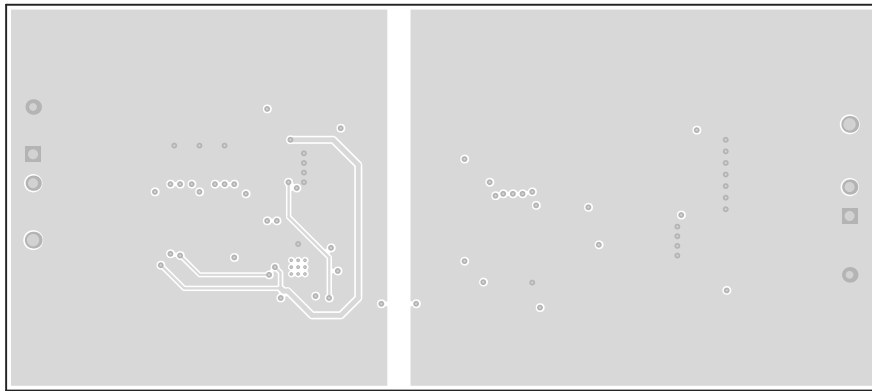
| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9720 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder | | | |
| PLOT NAME = Top Solder Mask | GENERATED : 5/20/2014 12:26:16 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9720 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer | | | |
| PLOT NAME = Top Layer | GENERATED : 5/20/2014 12:26:17 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9720 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = | | | |
| PLOT NAME = MidLayer1 | GENERATED : 5/20/2014 12:26:17 PM | TEXAS INSTRUMENTS | |



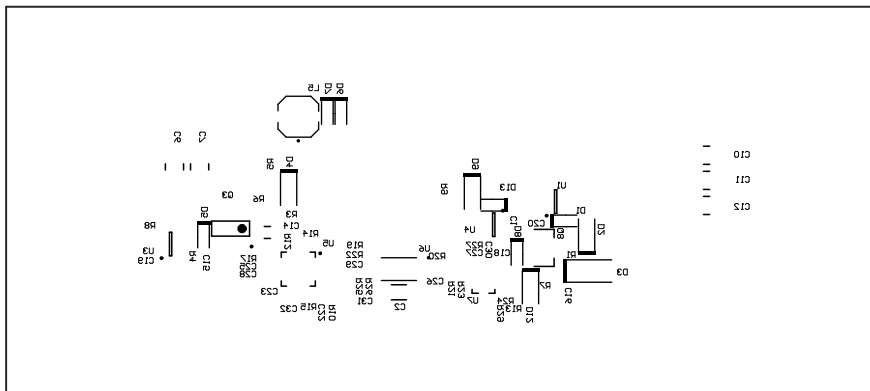
| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9720 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = | | | |
| PLOT NAME = MidLayer2 | GENERATED : 5/20/2014 12:26:18 PM | TEXAS INSTRUMENTS | |



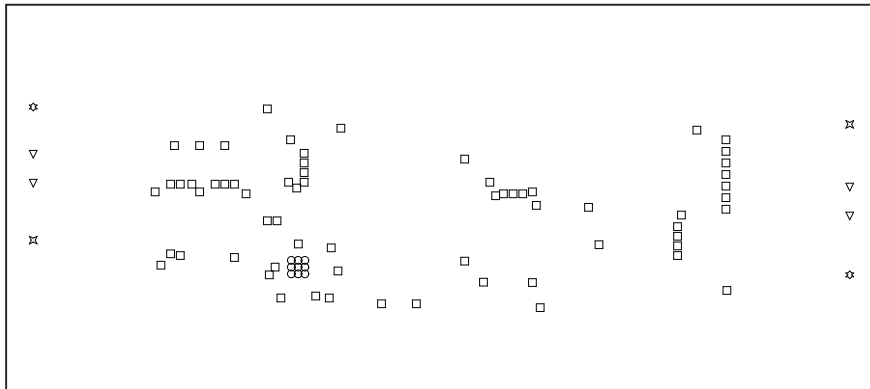
| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9720 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | | | |
| PLOT NAME = Bottom Layer | GENERATED : 5/20/2014 12:26:19 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9720 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 5/20/2014 12:26:20 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9720 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | | | |
| PLOT NAME = Bottom Overlay | GENERATED : 5/20/2014 12:26:20 PM | TEXAS INSTRUMENTS | |



| Symbol | Hit Count | Tool Size | Plated | Hole Type |
|----------|-----------|-------------------|--------|-----------|
| ○ | 9 | 7.874mil (0.2mm) | PTH | Round |
| □ | 65 | 12mil (0.305mm) | PTH | Round |
| ✱ | 2 | 40mil (1.016mm) | PTH | Round |
| ▽ | 4 | 51.181mil (1.3mm) | PTH | Round |
| ✕ | 2 | 63mil (1.6mm) | PTH | Round |
| 82 Total | | | | |

Drill Table

| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9720 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | | | |
| PLOT NAME = Drill Drawing | GENERATED : 5/20/2014 12:26:21 PM | TEXAS INSTRUMENTS | |



1000 (mil)

| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9720 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | | | |
| PLOT NAME = Board Dimensions | GENERATED : 5/20/2014 12:26:22 PM | TEXAS INSTRUMENTS | |

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